

# K3209-VB Datasheet N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
200	0.038 at $V_{GS} = 15 \text{ V}$	45	57	
200	0.043 at V <sub>GS</sub> = 10 V	40	57	

## **FEATURES**

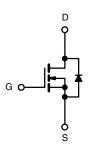
- TrenchFET® Power MOSFETS
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> and UIS Tested



### **APPLICATIONS**

- Power Supply
- · Lighting Systems





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$O_{A} = 25$ C, unless our	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	200	V	
Gate-Source Voltage		V <sub>GS</sub>	± 25	1 v	
Continuous Drain Current (T <sub>.I</sub> = 175 °C)	T <sub>C</sub> = 25 °C	1-	45		
Continuous Diam Current (1) = 175 C)	T <sub>C</sub> = 100 °C	I <sub>D</sub>	26	Δ.	
Pulsed Drain Current		I <sub>DM</sub>	150	Α	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	20		
Single Pulse Avalanche Energy <sup>a</sup>	L = 0.1 IIII1	E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C	В	55 <sup>b</sup>	14/	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	$P_{D}$	3.12	W	
Operating Junction and Storage Temperature Range		T <sub>I</sub> , T <sub>sta</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.75		

# Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α
Drain-Source On-State Resistance <sup>b</sup>		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.048		Ω
	R	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C		0.050		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.070		
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 3 A		0.092		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S
Dynamic <sup>a</sup>						
Input Capacitance	C <sub>iss</sub>			2800		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, F = 1 \text{ MHz}$		180		
Reverse Transfer Capacitance	C <sub>rss</sub>			80		
Total Gate Charge <sup>c</sup>	$Q_g$	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A		34	51	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			8		nC
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12		
Gate Resistance	$R_g$		0.5		2.9	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25	ns
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_L = 5.2 \Omega$ $I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		50	75	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			30	45	
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90	
Source-Drain Diode Ratings and Char	acteristics (7	T <sub>C</sub> = 25 °C)				
Pulsed Current	I <sub>SM</sub>				30	Α
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dI/dt = 100 A/µs		180	250	ns

### Notes:

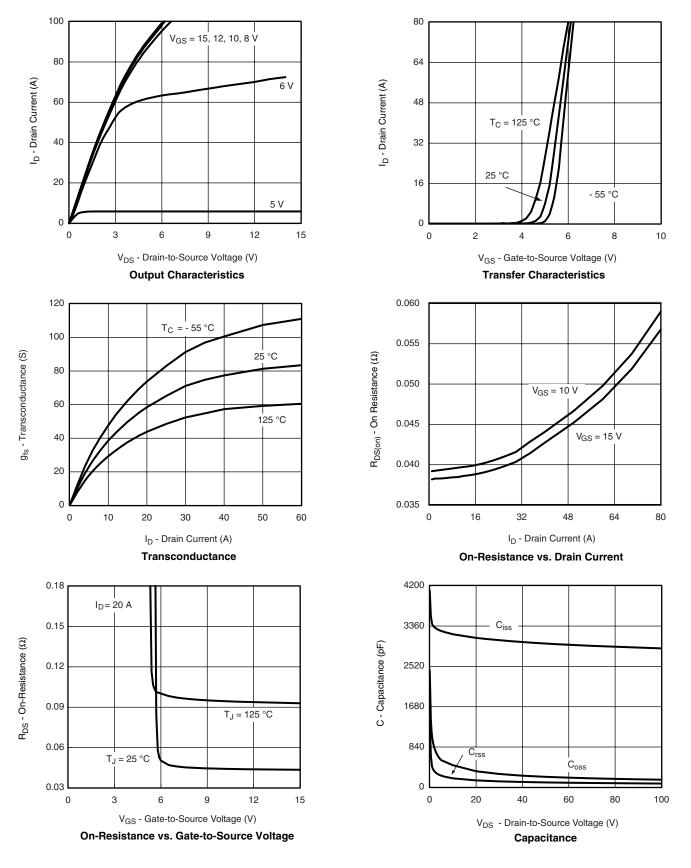
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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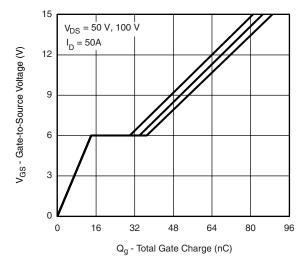
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



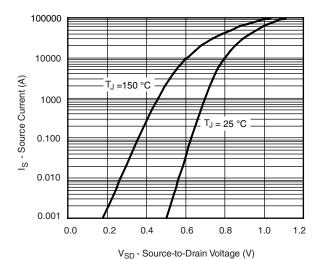
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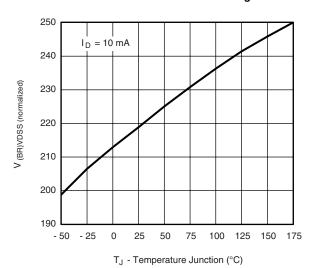
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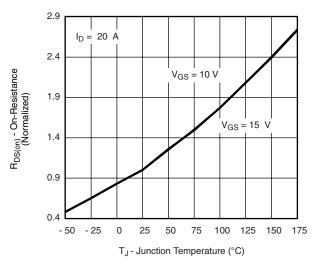




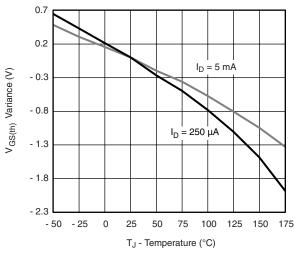
Source-Drain Diode Forward Voltage



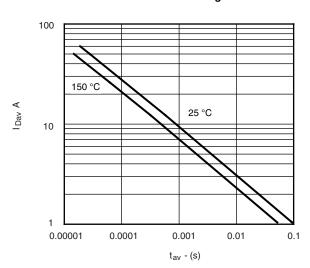
Drain Source Breakdown vs. Junction Temperature



### On-Resistance vs. Junction Temperature



Threshold Voltage



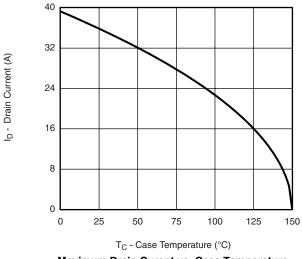
Single Pulse Avalanche Current Capability vs. Time

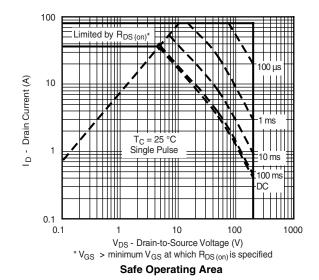
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Normalized Effective Transient Thermal Impedance

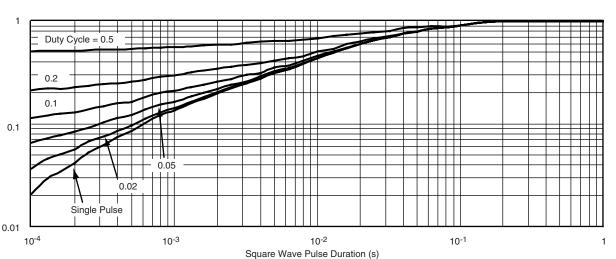


## THERMAL RATINGS





**Maximum Drain Curent vs. Case Temperature** 



Normalized Thermal Transient Impedance, Junction-to-Case

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